

A-SAP[™] Averatek Semi-Additive Process

Dramatic size and weight reduction over current state-of-the-art with 15micron (.6ml) trace and space







Standard PCB 0.8mm pitch - 20x20 grid 3 routing layers - L/S 3mil/3mil

ULTRA HIGH-DENSITY

- Improves Reliability: reduced layer count, micro vias and lamination cycles.
- Improved Signal Integrity: aspect ratios greater than 1:1 for metal traces.

HIGH PERFORMANCE PCBS

• Improved RF Performance: over traditional subtractive-etch processes.

PACKAGE SUBSTRATES & INTERPOSERS

- **Reduced Costs:** especially for complex, high-performance boards.
- Biocompatibility: capability for utilization of gold as conductive metal.



Capability in USA Today 75 microns



mSAP Cabability Today 25 microns

REDUCTION IN:

- Overall Size
- Number of Layers
- Number of Lamination Cycles



AVERATEK Capability Today 15 microns or better

Averatek

CHEMISTRY FOR THE A-SAP[™] PROCESS

LMI[™] - Liquid Metal Ink

Thin, Uniform, and Dense Electroless Deposition

- Ultra thin: a few nanometers thick
- Ultra dense: fully packed atomic film
- Conforms to any 3D surface at a nanometer scale
- Non-Aqueous: enables low-cost manufacturing
- Works for many different pure metals and alloys of those metals: copper, gold, silver, palladium, platinum, etc.





PROCESS FLOW



Averatek

Manufacturing technology for next-generation electronics capabilities. The development of key chemistries and advanced manufacturing processes for: very high density printed circuit boards, semiconductor packaging, RF and millimeter-wave passive components, simplified assembly to aluminum. Contact our leadership team today at tara@averatek.com

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